

100GbE Electrical Backplane / Cu Cabling Call-For-Interest Summary & Motion Closing Plenary Report

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IEEE 802.3 Working Group
Dallas, TX
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CFI Consensus Meeting Summary

- Attendance \approx 120 people
- Presentations
 - “The Need”, Howard Frazier, Broadcom.
 - “Technical Viability”, Adam Healey, LSI.
 - “Why Now?”, John D’Ambrosia, Force10 Networks.

Summary

- There is no 100GbE backplane solution, but.....
 - Networking equipment -
 - Faceplate capacities (10G, 40G, and 100G) are and will challenge current backplane solutions
 - Blade Servers
 - 40GbE Backplanes need to support future 100GbE servers
- 100GbE Cu Interfaces narrower than 100GBASE-CR10
 - May leverage a 100GbE backplane solution
 - Could enable multiple benefits – backwards compatibility with 40GbE, higher port density, and lower cost

Supporters

- Rick Rabinovich, Alcatel-Lucent
- Steve Trowbridge, Alcatel-Lucent
- Mike Li, Altera
- Shawn Searles, AMD
- Brian Kirk, Amphenol TCS
- Greg McSorley, Amphenol
- Brad Booth, Applied Micro
- Matt Brown, Applied Micro
- Rita Horner, Avago
- Brian Misek, Avago
- Charles Moore, Avago
- Jeff Slavick, Avago
- Yakov Belopolsky, Bel Stewart
- Paul Kish, Belden
- Wael Diab, Broadcom
- Howard Frazier, Broadcom
- Ali Ghiasi, Broadcom
- Arthur Marris, Cadence
- Hecham Elkhatib, Cinch
- Beth Donnay, Cisco
- Joel Goergen, Cisco
- Mark Nowell, Cisco
- Bhavesh A. Patel, Dell
- Ghani Abbas, Ericsson
- Vittal Balasubramanian, FCI
- Chris Cole, Finisar
- John D'Ambrosia, Force10 Networks
- Kapil Shrikhande, Force10 Networks
- Uri Cummings, Fulcrum Microsystems
- Ryan Latchman, Gennum
- Francois Tremblay, Gennum
- Dave Koenen, HP
- Steve Carlson, High Speed Design
- Orlando Savi, Hitachi
- Hidehiro Toyoda, Hitachi
- Jeff Lynch, IBM
- Pravin Patel, IBM
- Andy Moorwood, Infinera
- Andre Szczepanek, Inphi
- Dave Chalupsky, Intel
- Ilango Ganga, Intel
- Rich Mellitz, Intel
- Thananya Baldwin, IXIA
- Jerry Pepper, IXIA
- Jeff Maki, Juniper
- David Ofelt, Juniper
- Alan Flatman, LAN Technologies, UK
- Mike Bennett, LBNL
- Adam Healey, LSI
- Cathy Liu, LSI
- Marc Dupuis, Madison Cable
- Chris DiMinico, MC Communications/LEONI
- Oren Sela, Mellanox
- Howard Baumer, Mobius
- Galen Fromm, Molex
- Jay Neer, Molex
- Paul Vanderlaan, Nexans
- Fanny Minarsky, Octoscope
- Shimon Muller, Oracle
- Ron Nordin, Panduit
- Pat Diamond, Semtech
- George Eaton, Semtech
- Ed Cady, Siemon Company
- Valerie Maguire, Siemon Company
- George Zimmerman, Solarflare
- Sanjay Kasturia, Teranetics
- Karl Muth, Texas Instruments
- Iain Robertson, Texas Instruments
- Mike Fogg, Tyco Electronics
- Nathan Tracy, Tyco Electronics
- Jeff Lapak, UNH-IOL
- Frank Chang, Vitesse
- Ziad Hatab, Vitesse
- George Noh, Vitesse
- Atul Sharma, Volex
- Takeshi Nishimura, Yamaichi
- Marek Hajduczenia, ZTE

Summary of Straw Polls

- Call-For-Interest

- Should a Study Group be formed for “100GbE Electrical Backplanes and Cu Cable Interface”?

Results: Y: 95 N: 0 A: 8

- Participation

- I would participate in the “100GbE Electrical Backplane and Cu Cable Interface” Study Group in IEEE 802.3.

Results: 64

- My company would support participation in the “100GbE Electrical Backplane and Cu Cable Interface” Study Group in IEEE 802.3

Results: 43

Motion

- Move the IEEE 802.3 Working Group authorizes the formation of a study group for “100GbE Electrical Backplane and Twinaxial Copper Cable Assemblies.”

M: John D’Ambrosia

S: Adam Healey

>50%

802.3 Voters: Y: 59 N: 0 A: 1

Motion Passes